

What is claimed is

5 1. A circuit module comprising:

A carrier;

10 stacks of circuit chips arranged on a surface of the carrier  
and including several circuit chips arranged in different  
layers,

wherein the circuit chips are grouped in different groups,  
wherein the groups are not active at the same time,

15 wherein the circuit chips are arranged such that circuit  
chips belonging to the same group are arranged in different  
layers in adjacent stacks.

20 2. Circuit module according to claim 1, wherein stacks of  
circuit chips are arranged on a first surface and a second  
surface of the carrier.

25 3. Circuit module according to claim 1, wherein the circuit  
module is a memory module and the circuit chips are memory  
chips.

30 4. Circuit module according to claim 3, wherein the memory  
module is a DIMM and the memory chips are DRAMs.

5. Circuit module according to claim 3, wherein the groups  
into which the circuit chips are grouped are respective  
memory banks.

35 6. Circuit module according to claim 1, further comprising  
means to activate the circuit chips belonging to the same  
group.

7. Circuit module according to claim 6, wherein the means to activate the circuit chips belonging to the same group comprises a bank select signal.